PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	MDG/23/13840
1.3 Title of PCN	ASE KaoHsiung (Taiwan) LQFP 24x24 package copper palladium bonding wire introduction on STM32F2/F4/F7x and STM32H5/H7x listed products
1.4 Product Category	STM32F2x, STM32F4x, STM32F7x, STM32H5x, STM32H7x
1.5 Issue date	2023-02-15

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	NEMETH KRISZTINA
2.1.2 Phone	+49 89460062210
2.1.3 Email	krisztina.nemeth@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), Bond wire material, diameter	ASE Kaohsiung (TAIWAN)

4. Description of change

	Old	New
4.1 Description	Current Wire bonding material: - ASE KaoHsiung (Taiwan) gold wire Current Glue material: - Sumitomo CRM 1076WA - YIZTECH 8143	New Wire bonding material : - ASE KaoHsiung (Taiwan) copper palladium wire Glue Material : - Sumitomo CRM 1076WA - YIZTECH 8143 Additional Glue material : - HITACHI EN4900G
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no impact on form, Fit, Function	

5. Reason / motivation for change

5.1 Motivation	To improve service
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	traceability ensured by ST Internal tools

7. Timing / schedule

7.1 Date of qualification results	2023-01-27
7.2 Intended start of delivery	2023-03-21
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	13840 MDG-GPM-RER2303-V1.0-PCN13840-ASEKH LQ24x24 Low cost wire introduction.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	**Issue Date**	2023-02-15

9. Attachments (additional documentations)

13840 Public product.pdf
13840 MDG-GPM-RER2303-V1.0-PCN13840-ASEKH LQ24x24 Low cost wire introduction.pdf
13840 PCN13840_Additional information.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	**10.1.2 Supplier Part No**	**10.1.2 Supplier Part No**
	STM32F207IFT6	
	STM32F207IGT6	
	STM32F407IGT6	
	STM32F407IGT7	
	STM32F417IET6	
	STM32F427IGT6	
	STM32F427IIT6	
	STM32F429IIT6	
	STM32F767IIT6	
	STM32F777IIT6	
	STM32H743IIT6	

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Public Products List

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PCN Title : ASE KaoHsiung (Taiwan) LQFP 24x24 package copper palladium bonding wire introduction on STM32F2/F4/F7x and STM32H5/H7x listed products
PCN Reference : MDG/23/13840

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32F207IET6	STM32H7A3IGT6	STM32F417IGT7
STM32F746IGT7	STM32F469IIT6	STM32F769IGT6
STM32F407IGT6	STM32F756IGT6	STM32F417IGT6
STM32H753IIT6	STM32F722IET6	STM32F207ICT6
STM32F217IET6	STM32F217IGT7	STM32F407IET6
STM32H743IGT6	STM32F745IET6	STM32F207IFT6
STM32F207IGT6	STM32H742IIT6	STM32F469IGT6
STM32F745IET7	STM32F777IIT6	STM32F207IGT7
STM32F746IET6	STM32F723IET7	STM32H755IIT3
STM32H7B3IIT6Q	STM32H745IIT3	STM32F745IGT6
STM32F427IIT7	STM32F407IGT7	STM32F417IET6
STM32F437IIT7	STM32F722IET7	STM32H757IIT6
STM32F479IIT6	STM32F217IGT6	STM32F746IGT6
STM32H743IIT6	STM32F723IET6	STM32H747IGT6
STM32H7A3IIT6	STM32F437IIT6	STM32F427IIT6
STM32F765IGT6	STM32F427IGT6	STM32F777IIT7
STM32F429IGT6	STM32F765IIT7	STM32F723ICT6
STM32H755IIT6	STM32H7A3IIT6Q	STM32F439IIT6
STM32H735IGT6	STM32F429IIT6	STM32F733IET6
STM32H725IGT6	STM32H745IGT6	STM32F779IIT6
STM32F767IGT6	STM32H725IET6	STM32F439IGT6
STM32H730IBT6Q	STM32F437IGT6	STM32F429IET6
STM32H745IIT6	STM32H747IIT6	STM32F769IIT6
STM32H7B0IBT6	STM32F765IIT6	STM32F732IET6
STM32H750IBT6	STM32F722ICT6	STM32F767IIT6
STM32H7B3IIT6		

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